

Application No.: 10/713,028Docket No.: 2336-221

ABSTRACT

~~Disclosed is a~~ A method for fabricating Surface Acoustic Wave filter packages ~~using~~ uses a package sheet having an outline pattern and anti-bur holes ~~and a package sheet used therein~~. In the package sheet for a Surface Acoustic Wave filter package, ~~the~~ the ~~[[an]]~~ outline pattern is formed along outer peripheries of ~~predetermined areas to be mounted with~~ chip mounting areas where a plurality of SAW filter chips ~~are to be mounted~~. The outline pattern is contacted with a metal shield layer formed on the SAW filter chips and a predetermined region of the package sheet. Circular anti-bur holes ~~cover~~ are located at the corners of the chip mounting areas ~~and on to be mounted with the~~ SAW filter chips ~~and are intersected by cutting lines functioning as reference lines for cutting along~~ which the sheet is to be singulated into a plurality of individual SAW filter packages.